



Press Release

X-FAB Opens New Cleanroom at its Malaysian Site

Expansion more than doubles capacity for its popular 180nm BCD-on-SOI technology

Kuching, Sarawak, Malaysia – September 12, 2025

X-FAB, the leading analog/mixed-signal and specialty foundry, today celebrated the grand opening of a new state-of-the-art manufacturing line at its Sarawak facility. The ceremony was officiated by the Prime Minister of Malaysia, YAB Dato' Seri Anwar Ibrahim, and the Sarawak Premier, YAB Datuk Patinggi Tan Sri Abang Johari Tun Openg.

This major expansion – representing a \$600 million investment – marks a significant milestone for X-FAB Sarawak. The project added 6,000 square meters of cleanroom space and was completed in just two years, from groundbreaking to the first production lots. As a result, the site's monthly wafer start capacity has increased from 30,000 to 40,000, with a key highlight being the more than doubling of capacity for X-FAB's highly sought-after 180nm BCD-on-SOI technology (XT018).

BCD-on-SOI technology is superior in many aspects when compared to conventional bulk BCD technologies, making it attractive to designers. Key advantages include virtual latch-up free circuits, strong EMC performance (due to complete isolation with buried oxide/DTI) and simplified handling of below ground transients. The XT018 platform features a comprehensive portfolio of voltage options from 10 V to 375 V as well as a full range of automotive Grade-0 qualified Non-Volatile-Memory options. It is specifically designed for next generation automotive, industrial and medical applications operating in extreme temperature ranges from -40 to 175 °C.

X-FAB's XT018 is ideally suited for smart motor drivers, smart LED drivers, and battery management systems, enabling high performance and compact design in demanding environments. Additionally, the company's BCD-on-SOI solutions are a perfect fit for



ultrasonic probe heads used in real-time medical imaging, where precision, reliability, and miniaturization are critical.

"Our 180nm BCD-on-SOI technology has become a cornerstone for innovation across automotive, industrial, and medical applications, with over 100 active customers relying on it today. This expansion is a strategic step forward – ensuring that our capacity keeps pace with growing global demand whilst positioning us to capture new opportunities" said Rudi De Winter, CEO of X-FAB Group. "I am grateful for the continued support from the Sarawak government and the Malaysian Investment Development Authority enabling us to achieve this major milestone for the future success of the entire X-FAB Group."

The new manufacturing line is now operational and will serve X-FAB's global customer base across the automotive, industrial, and medical sectors.

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Glossary

BCD – Bipolar CMOS-DMOS

MIDA – Malaysian Investment Development Authority



About X-FAB

X-FAB is a global foundry group providing a comprehensive set of specialty technologies and design IP to enable its customers to develop world-leading semiconductor products that are manufactured at X-FAB's six wafer fabs located in Malaysia, Germany, France, and the United States. With its expertise in analog/mixed-signal technologies, microsystems/MEMS, Photonics, silicon carbide (SiC) and gallium nitride (GaN), X-FAB is the development and manufacturing partner for its customers, primarily serving the automotive, industrial and medical end markets. X-FAB has approximately 4,500 employees and has been listed on Euronext Paris since April 2017 (XFAB). For more information, please visit www.xfab.com.

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